

# 2SB0767G

## Silicon PNP epitaxial planar type

For low-frequency output amplification

Complementary to 2SD0875G

### ■ Features

- Large collector power dissipation  $P_C$
- High collector-emitter voltage (Base open)  $V_{CEO}$
- Mini type package, allowing downsizing of the equipment and automatic insertion through the tape packing and the magazine packing

### ■ Package

- Code  
MiniP3-F2
- Pin Name  
1: Base  
2: Collector  
3: Emitter

### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	$V_{CBO}$	-80	V
Collector-emitter voltage (Base open)	$V_{CEO}$	-80	V
Emitter-base voltage (Collector open)	$V_{EBO}$	-5	V
Collector current	$I_C$	-0.5	A
Peak collector current	$I_{CP}$	-1	A
Collector power dissipation *	$P_C$	1	W
Junction temperature	$T_j$	150	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-55 to +150	$^\circ\text{C}$

### ■ Marking Symbol: C

Note) \*: Print circuit board: Copper foil area of  $1\text{ cm}^2$  or more, and the board thickness of 1.7 mm for the collector portion.

### ■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

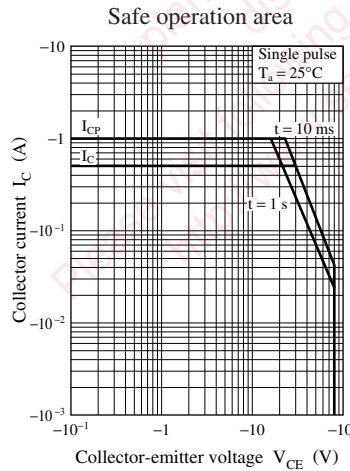
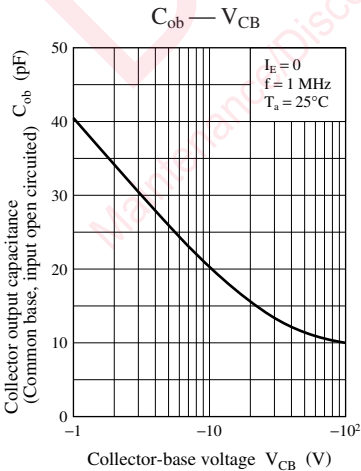
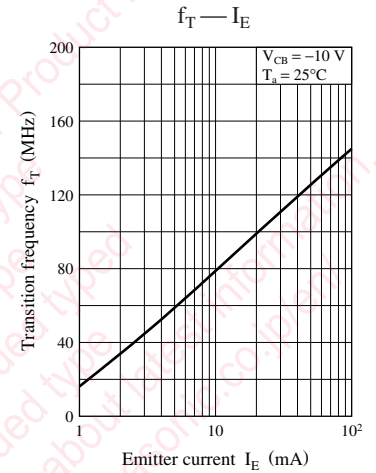
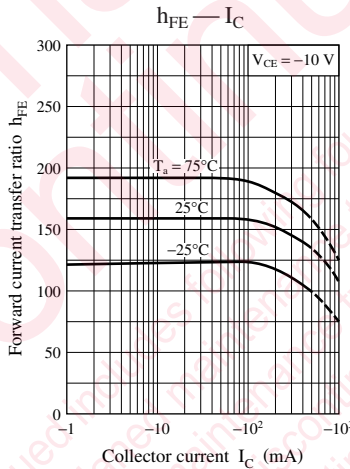
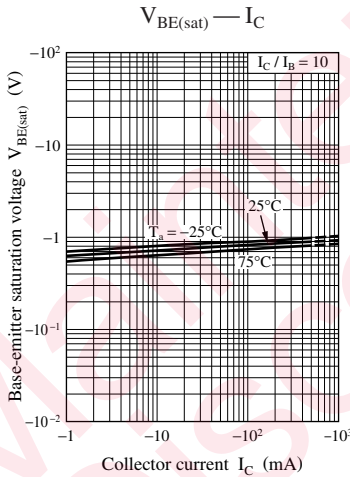
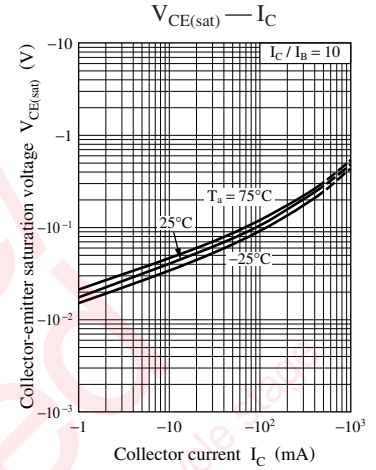
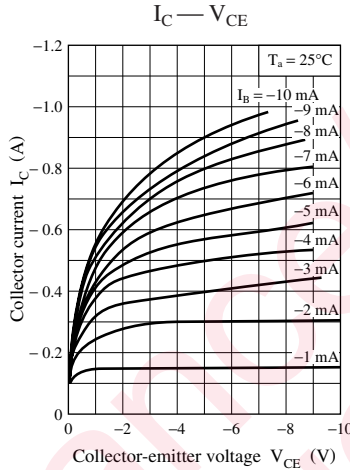
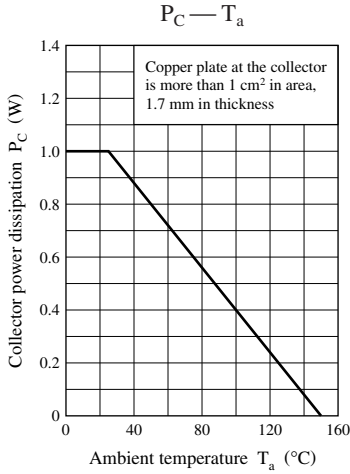
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector-base voltage (Emitter open)	$V_{CBO}$	$I_C = -10\ \mu\text{A}$ , $I_E = 0$	-80			V
Collector-emitter voltage (Base open)	$V_{CEO}$	$I_C = -100\ \mu\text{A}$ , $I_B = 0$	-80			V
Emitter-base voltage (Collector open)	$V_{EBO}$	$I_E = -10\ \mu\text{A}$ , $I_C = 0$	-5			V
Collector-base cutoff current (Emitter open)	$I_{CBO}$	$V_{CB} = -20\ \text{V}$ , $I_E = 0$			-0.1	$\mu\text{A}$
Forward current transfer ratio *1	$h_{FE1}$ *2	$V_{CE} = -10\ \text{V}$ , $I_C = -150\ \text{mA}$	90		220	—
	$h_{FE2}$	$V_{CE} = -5\ \text{V}$ , $I_C = -500\ \text{mA}$	50	100		
Collector-emitter saturation voltage *1	$V_{CE(sat)}$	$I_C = -300\ \text{mA}$ , $I_B = -30\ \text{mA}$		-0.2	-0.4	V
Base-emitter saturation voltage *1	$V_{BE(sat)}$	$I_C = -300\ \text{mA}$ , $I_B = -30\ \text{mA}$		-0.85	-1.20	V
Transition frequency	$f_T$	$V_{CB} = -10\ \text{V}$ , $I_E = 50\ \text{mA}$ , $f = 200\ \text{MHz}$		120		MHz
Collector output capacitance (Common base, input open circuited)	$C_{ob}$	$V_{CB} = -10\ \text{V}$ , $I_E = 0$ , $f = 1\ \text{MHz}$		20	30	pF

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2. \*1: Pulse measurement

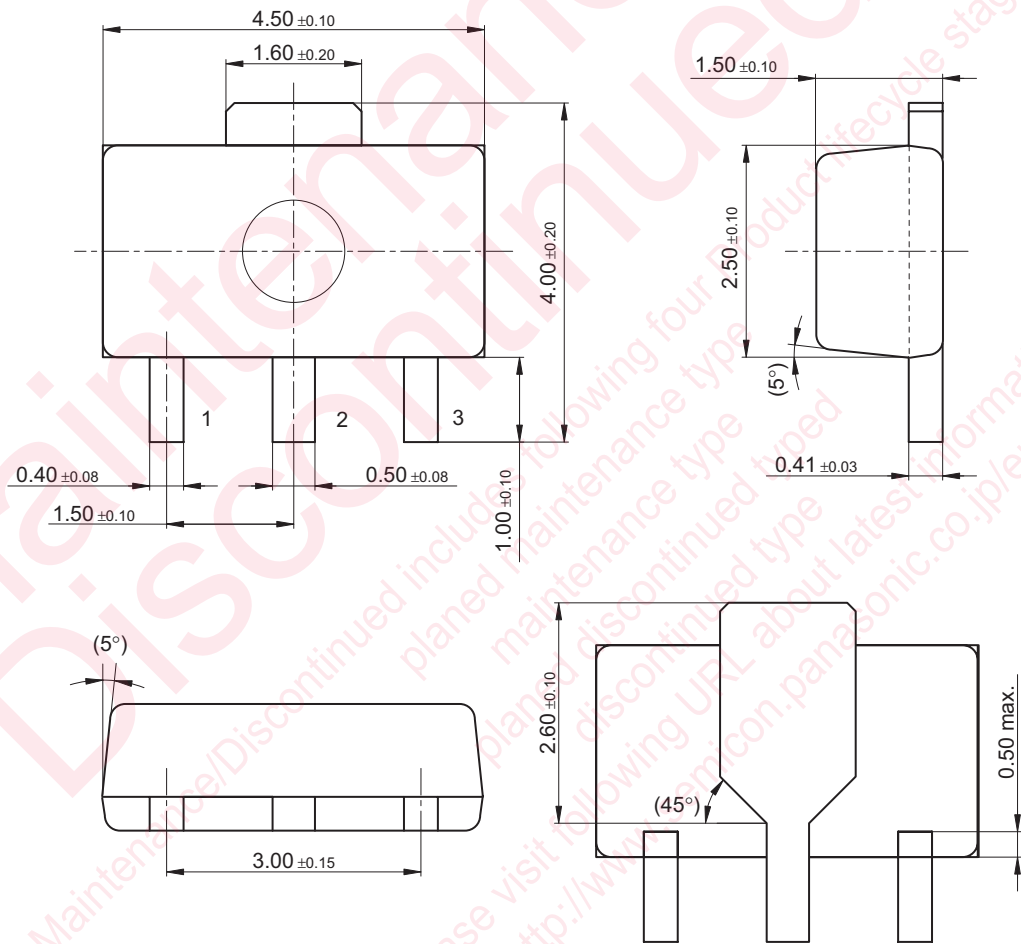
\*2: Rank classification

Rank	Q	R
$h_{FE1}$	90 to 155	130 to 220



MiniP3-F2

Unit: mm



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